

**REMARKS**

Applicant hereby responds to the Examiner's rejections based upon the newly cited Kato reference. Applicant submits that neither Kato nor any of the remaining references of record provide any teaching or suggestion regarding the presently claimed subject matter. One significant feature of the present invention is that a plurality of previously manufactured semiconductor chips, regardless of whether they are the same type or of different types of chips, are tested and separated from their original respective wafers. Significantly, only those chips that are not defective are further processed and formed into the specific structures now specified in the claims. The cited references of record provide no teaching or suggestion regarding this advance in the art.

The Applicant has realized significant advantages over existing manufacturing techniques by eliminating the wasteful process of forming expensive bump connections on all chips in a common wafer. Rather, the inventor has determined that significant cost savings can be achieved by forming a pseudo wafer of non-defective chips such that only the non-defective chips are further processed as a wafer for providing bump contacts, for example. See specifically page 17, lines 15-25 of the instant specification.

The references of record fail to either teach or suggest this advance in the art. Indeed, the Kato reference actually teaches away from the present invention because every single embodiment described in the Kato reference specifies that a single previously manufactured original wafer in which a plurality of chips is secured to an adhesive sheet. Furthermore, in each and every embodiment of the Kato reference, the solder bumps are already formed on

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the contacts. See specifically figures 6A-11A. Kato thus does not provide several of the advantages that are described and claimed in the instant application.

In light of the foregoing, Applicant respectfully requests that the Examiner now allow all claims in the instant application.

Respectfully submitted,

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